

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10552441			
<b>Filing Date:</b>	07-Oct-2005			
<b>Title of Invention:</b>	Epoxy resin molding material for sealing use and semiconductor device			
<b>First Named Inventor/Applicant Name:</b>	Ryoichi Ikezawa			
<b>Filer:</b>	William Ivan Solomon/Stacey Keaton			
<b>Attorney Docket Number:</b>	1204.45467X00			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 1 month with \$0 paid	1251	1	120	120

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				120